Sue Ann Bidstrup Allen

List of Publications by Year in Descending Order

37 papers	822 citations	15 h-index	28 g-index
38 ext. papers	899 ext. citations	3.3 avg, IF	3.34 L-index

#	Paper	IF	Citations
37	Vertically integrated high voltage Zn-Air batteries enabled by stacked multilayer electrodeposition. *Journal of Power Sources*, **2020**, 449, 227566	8.9	1
36	3D lithium ion battery fabrication via scalable stacked multilayer electrodeposition. *Journal of Micromechanics and Microengineering*, **2019**, 29, 055006	2	2
35	Model-assisted development of microfabricated 3D Ni(OH) 2 electrodes with rapid charging capabilities. *Journal of Power Sources*, **2017**, 358, 101-111	8.9	5
34	Biodegradable magnesium/iron batteries with polycaprolactone encapsulation: A microfabricated power source for transient implantable devices. *Microsystems and Nanoengineering*, **2015**, 1,	7.7	59
33	A MEMS-enabled biodegradable battery for powering transient implantable devices **2014**,		15
32	. *Journal of Microelectromechanical Systems*, **2014**, 23, 1281-1289	2.5	13
31	Enhanced photo-patterning of polymer dielectrics via imprint lithography. *Microelectronic Engineering*, **2012**, 93, 19-26	2.5	3
30	Electroless Deposition of Copper on Organic and Inorganic Substrates Using a Sn/Ag Catalyst. *Journal of the Electrochemical Society*, **2012**, 159, D386-D392	3.9	22
29	Imprint lithography enabling ultra-low loss coaxial interconnects. *Microelectronic Engineering*, **2011**, 88, 240-246	2.5	5
28	Photodefinable Epoxycyclohexyl Polyhedral Oligomeric Silsesquioxane. *Journal of Electronic Materials*, **2010**, 39, 149-156	1.9	9
27	Aqueous-Develop, Photosensitive Polynorbornene Dielectric: Properties and Characterization. *Journal of Electronic Materials*, **2009**, 38, 778-786	1.9	16
26	Adhesion Enhancement Between Electroless Copper and Epoxy-based Dielectrics. *IEEE Transactions on Advanced Packaging*, **2009**, 32, 758-767		15
25	All-Copper Chip-to-Substrate Interconnects Part II. Modeling and Design. *Journal of the Electrochemical Society*, **2008**, 155, D314	3.9	15
24	Air-Gaps for High-Performance On-Chip Interconnect Part II: Modeling, Fabrication, and Characterization. *Journal of Electronic Materials*, **2008**, 37, 1534-1546	1.9	6
23	Air-Gaps for High-Performance On-Chip Interconnect Part I: Improvement in Thermally Decomposable Template. *Journal of Electronic Materials*, **2008**, 37, 1524-1533	1.9	11
22	UV-induced porosity using photogenerated acids to catalyze the decomposition of sacrificial polymers templated in dielectric films. *Journal of Materials Chemistry*, **2007**, 17, 873-885		7
21	Electron-beam hardening of thin films of functionalized polynorbornene copolymer. *Journal of Electronic Materials*, **2006**, 35, 1112-1121	1.9	4

20	Low-Temperature Bonding of Copper Pillars for All-Copper Chip-to-Substrate Interconnections. *Electrochemical and Solid-State Letters*, **2006**, 9, C192		30
19	Plasma Treatment and Surface Analysis of Polyimide Films for Electroless Copper Buildup Process. *Journal of the Electrochemical Society*, **2005**, 152, F162	3.9	40
18	Improved fabrication of micro air-channels by incorporation of a structural barrier. *Journal of Micromechanics and Microengineering*, **2005**, 15, 35-42	2	31
17	Hydrophobic/hydrophilic surface modification within buried air channels. *Journal of Vacuum Science & Technology an Official Journal of the American Vacuum Society B, Microelectronics Processing and Phenomena*, **2004**, 22, 953		10
16	Crosslinking and decomposition reactions of epoxide-functionalized polynorbornene. II. Impact of reactions on mechanical properties. *Journal of Applied Polymer Science*, **2004**, 91, 1020-1029	2.9	11
15	Photosensitive polynorbornene based dielectric. II. Sensitivity and spatial resolution. *Journal of Applied Polymer Science*, **2004**, 91, 3031-3039	2.9	12
14	Photosensitive polynorbornene based dielectric. I. Structure–property relationships. *Journal of Applied Polymer Science*, **2004**, 91, 3023-3030	2.9	21
13	Photoinitiation systems and thermal decomposition of photodefinable sacrificial materials. *Journal of Applied Polymer Science*, **2003**, 88, 1186-1195	2.9	9
12	Crosslinking and decomposition reactions of epoxide functionalized polynorbornene. Part I. FTIR and thermogravimetric analysis. *Journal of Applied Polymer Science*, **2003**, 89, 568-577	2.9	43
11	Fabrication of Microchannels Using Polynorbornene Photosensitive Sacrificial Materials. *Journal of the Electrochemical Society*, **2003**, 150, H205	3.9	26
10	Chemically Bonded Porogens in Methylsilsesquioxane. *Journal of the Electrochemical Society*, **2002**, 149, F161	3.9	43
9	Chemically Bonded Porogens in Methylsilsesquioxane. *Journal of the Electrochemical Society*, **2002**, 149, F171	3.9	23
8	Lithographic Characteristics and Thermal Processing of Photosensitive Sacrificial Materials. *Journal of the Electrochemical Society*, **2002**, 149, G555	3.9	11
7	Porous Methylsilsesquioxane for Low-k Dielectric Applications. *Electrochemical and Solid-State Letters*, **2001**, 4, F25		55
6	Comparison of plasma chemistries and structure-property relationships of fluorocarbon films deposited from octafluorocyclobutane and pentafluoroethane monomers. *Journal of Vacuum Science & Technology an Official Journal of the American Vacuum Society B, Microelectronics Processing and Phenomena*, **2001**, 19, 439		18
5	Fabrication of microchannels using polycarbonates as sacrificial materials. *Journal of Micromechanics and Microengineering*, **2001**, 11, 733-737	2	78
4	Dual capacitor technique for measurement of through-plane modulus of thin polymer films. *Journal of Polymer Science, Part B: Polymer Physics*, **2000**, 38, 1634-1644	2.6	12
3	In situ measurement of the thermal expansion behavior of benzocyclobutene films. *Journal of Polymer Science, Part B: Polymer Physics*, **1999**, 37, 311-321	2.6	12

2	Functionalized polynorbornene dielectric polymers: Adhesion and mechanical properties. *Journal of Polymer Science, Part B: Polymer Physics*, **1999**, 37, 3003-3010	2.6	128
1	Functionalized polynorbornene dielectric polymers: Adhesion and mechanical properties **1999**, 37, 3003		1